

DOCKET NO.: 240882US0

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF :
TOMOHISA KONNO ET AL : EXAMINER: RACHUBA, MAURINA T.
SERIAL NO.: 10/626,521 :
FILED: JULY 25, 2003 : GROUP ART UNIT: 3723
FOR: AQUEOUS DISPERSION FOR :
CHEMICAL MECHANICAL POLISHING
AND PRODUCTION PROCESS OF
SEMICONDUCTOR DEVICE

REQUEST FOR RECONSIDERATION

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Office Action dated February 13, 2008, reconsideration and allowance are respectfully requested in view of the following remarks.

Claims 1-11, 13-15 and 18-21 are pending, claims 1-6, 8, 10 and 11 having been withdrawn from consideration.

Rejection Under 35 U.S.C. §103

The Office Action rejects claims 7, 9, 13-15 and 18-21 under 35 U.S.C. §103(a) over U.S. Patent No. 7,087,530 to Motonari et al. ("Motonari"). Applicants respectfully traverse the rejection.

Claim 7 recites "[a] process for producing a semiconductor device, comprising: polishing a surface of a semiconductor material with an aqueous dispersion for chemical mechanical polishing comprising abrasive grains and a heterocyclic compound; wherein: the